

# Hybrid Sintering

## Features

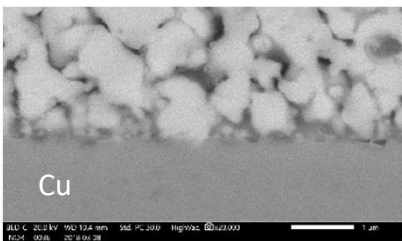
- Pressure-less sintering
- Excellent bonding to Cu
- Good reliability & High thermal conductivity
- RoHS Compliance & Pb solder replacement



## Die Attach

### TS-9853G

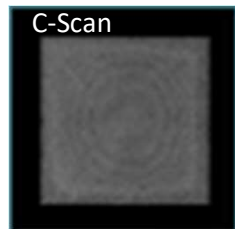
7x7mm Si(Ag BSM)/Bare CuLF



**Curing Condition:**  
200°C60min / 250°C 60min in N<sub>2</sub>  
**TC Condition:**  
-55°C 30min ⇄ 150°C 30min

### Bonding to Cu LF

TC 2000x



No delamination

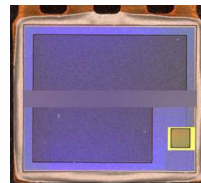
## Clip Attach\*

\*Collaborating with CITC

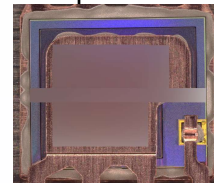


### Bonding to Cu Clip

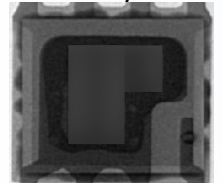
Die Attach



Clip Attach



X-ray



Cross-section after TC 2000x



No delamination

